



Industrial Adhesives Catalog

Perfecting the Power to Connect with a Single Drop

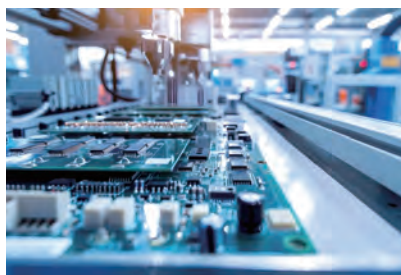
Speed × Power
Cyanoacrylate Adhesives

Quick × Strong
Epoxy Adhesives

Create × Innovate
Anaerobic Adhesives
& Light-Cure Adhesives



Quick & Strong Epoxy Adhesives



We continue the challenge
of developing people and
the environmental friendly
adhesives

ALTECO epoxy adhesives deliver excellent performance, including high bonding strength, heat resistance, and chemical resistance. A wide range of grades is available to meet diverse requirements, from electrical and electronic applications to industrial equipment use.

Excellent Adhesion Compatible with a wide range of substrates.
Excellent Durability Excellent heat resistance, water resistance, weather resistance, and chemical resistance.
Electrical Insulation Does not conduct electricity. Provides excellent insulating properties.
Low Curing Shrinkage Solvent free, virtually no shrinkage upon curing.
Environmental Regulation Compliant Compliant with various environmental regulations.

*For details, contact us.

Skin Irritation Prevention

Epoxy adhesives may cause irritation to the skin, eyes, throat, and mucous membranes, leading to rashes or itching.

Repeated exposure may result in sensitization. Use with caution.

- (1) Use in ventilated area. Wear safety goggles, glasses, masks, and gloves.
- (2) Clean the work environment (desk, containers), and immediately wipe off any spills or residues.
- (3) After finishing work, wash your hands thoroughly with soap and water.
- (4) If skin irritation occurs, consult a doctor.



Epoxy Adhesives



Fast Curing (Thixotropic) Two-Component

Fast-curing, thixotropic, non-sagging two-component epoxy resin adhesive.

Fast

Fast curing epoxy adhesives cured in 5 and 30 minutes after mixing a base resin and a hardener.

Thixotropic

Translucent no sag. Allows buildup and gap filling bonding.



Product Number	F-05		F-30	
	Base Resin	Hardener	Base Resin	Hardener
Applications	General purpose bonding (Metal, Glass, Ceramics, Wood, Plastics)		General purpose bonding (Metal, Glass, Ceramics, Wood, Plastics)	
Features	<ul style="list-style-type: none"> ● 5minutes curing ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 		<ul style="list-style-type: none"> ● 30minutes curing ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	Milky White	White Translucent	Milky White	White Translucent
Color After Curing	Milky White		Milky White	
Main Component	Modified epoxy resin	Modified thiol	Modified epoxy resin	Modified thiol
Viscosity (mPa·s / 25℃)	Paste	Paste	Paste	Paste
Specific Gravity (d ₄ ²⁰)	1.16	1.13	1.20	1.20
Mixing Ratio	100 : 100		100 : 100	
Open Time (25℃)	3min		20min	
Curing Time	5min		30min	
Tensile Shear Strength (N/mm ²)	15		15	
Hardness (Shore D)	78		78	
Shelf Life	1 year		1 year	
Volume / Packaging	70g set Aluminum tube 1kg set Plastic laminated tube		45g set Aluminum tube 1kg set Plastic laminated tube	

Test method: In accordance with JIS K 6833 (1994), general test methods for adhesives. In accordance with JIS K 6850 (1999), tensile shear adhesive strength testing method for adhesives and rigid substrates.

Fast Curing (Clear) Two-Component

Transparent formula that helps conceal applied areas. Fast curing two-component epoxy adhesive.

Fast

Fast curing epoxy adhesives cured in 5 and 30 minutes after mixing a base resin and a hardener.

Clear

Transparent formula that helps conceal applied areas.



Product Number	F-05C		F-30C	
	Base Resin	Hardener	Base Resin	Hardener
Applications	Suitable for general bonding applications requiring transparency. (Metal, Glass, Ceramics, Wood, Plastics)		Suitable for general bonding applications requiring transparency. (Metal, Glass, Ceramics, Wood, Plastics)	
Features	<ul style="list-style-type: none"> ● 5minutes curing ● Clear type of F-05 ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 		<ul style="list-style-type: none"> ● 30minutes curing ● Clear type of F-30 ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	Transparent	Yellow, Transparent	Transparent	Yellow, Transparent
Color After Curing	Pale Yellow, Transparent		Pale Yellow, Transparent	
Main Component	Modified epoxy resin	Modified thiol	Modified epoxy resin	Modified thiol
Viscosity (mPa·s / 25℃)	15000	13000	15000	16000
Specific Gravity (d ₄ ²⁰)	1.17	1.13	1.17	1.14
Mixing Ratio	100 : 100		100 : 100	
Open Time (25℃)	3min		20min	
Curing Time	5min		30min	
Tensile Shear Strength (N/mm ²)	10		15	
Hardness (Shore D)	80		80	
Shelf Life	1 year		1 year	
Volume / Packaging	1kg set Plastic laminated tube		1kg set Plastic laminated tube	

Epoxy Adhesives

For Molding Two-Component

A two-component epoxy adhesive that cures to a highly transparent, glossy finish.

■ Transparency

Offers superior transparency and resistance to yellowing; ideal for casting, coating, and potting.

■ Low Viscosity

The low viscosity enables precise filling of small areas and makes it suitable for coating when applied with brushes or spatulas.



Product Number	R-2007/H-1040		R-2007/H-2002	
	Base Resin	Hardener	Base Resin	Hardener
Applications	<ul style="list-style-type: none"> ● Bonding, Molding, Potting, Coating ● Small size molding ● Molding of electronic components ● Bonding of glass ornaments 		<ul style="list-style-type: none"> ● Bonding, Molding, Potting, Coating ● Medium to large size molding ● For bonding and casting where transparency is required. 	
Features	<ul style="list-style-type: none"> ● Room to medium temperature curing ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 		<ul style="list-style-type: none"> ● Curing conditions : Gel at room temperature after 24h, secondary cure at elevated temperature. ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	Transparent	Transparent	Transparent	Transparent
Color After Curing	Transparent		Transparent	
Main Component	Modified epoxy resin	Modified polyamine	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	3000	50	3000	80
Specific Gravity (d ₄ ²⁰)	1.17	0.99	1.17	0.98
Mixing Ratio	100 : 40		100 : 40	
Pot Life at 25°C	45min		5min	
Curing Time	24h		48h	
Tensile Shear Strength (N/mm ²)	15		14	
Hardness (Shore D)	82		80	
Shelf Life	1year		1year	
Volume / Packaging	Base resin : 1kg Plastic jar Hardener: 400g Plastic jar		Base resin : 1kg Plastic jar Hardener: 400g Plastic jar	

Test method: In accordance with JIS K 6833 (1994), general test methods for adhesives. In accordance with JIS K 6850 (1999), tensile shear adhesive strength testing method for adhesives and rigid substrates.

In Cartridge Two-Component

Enables simultaneous and accurate measuring, mixing, and dispensing.

■ High Work Efficiency

In 2-in-1 cartridge.
Mix and dispense by setting in cartridge gun.



The specialized dispensing gun is not included.

Product Number	MAZERUN52		MAZERUN300T	
	Base Resin	Hardener	Base Resin	Hardener
Applications	General purpose bonding (Metal, Glass, Ceramics, Wood, Stone, Concrete)		<ul style="list-style-type: none"> ● For bonding and fixturing metal and wood construction materials ● Bonding and repair of car stop block, marbles, bricks, concrete blocks ● Insulation bonding and fixturing of electric parts, magnet 	
Features	<ul style="list-style-type: none"> ● Room temperature curing ● No stain on white stones ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 		<ul style="list-style-type: none"> ● Room temperature curing ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	White	Beige	White	Black
Color After Curing	Beige		Gray	
Main Component	Modified epoxy resin	Modified polyamine	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	Paste	Paste	Paste	Paste
Specific Gravity (d ₄ ²⁰)	1.34	1.16	1.17	1.10
Mixing Ratio	100 : 100		100 : 100	
Pot Life at 25°C	30min		10min	
Curing Time	24h		24h	
Tensile Shear Strength (N/mm ²)	20		14	
Hardness (Shore D)	77		80	
Shelf Life	1year		1year	
Volume / Packaging	50ml Cartridge		300ml Cartridge	



For General Purpose Two-Component

Two-component epoxy adhesive with a 1:1 weight ratio.
Suitable for bonding a wide range of materials.

Application on Large Area

Extended curing time enables wide-area application
and allows for easy removal of any excess material.

Strong Bonding on Wide Range of Materials

Bonds well to metal, glass, plastics, ceramics, and wood.



Product Number	6100	
	Base Resin	Hardener
Applications	General purpose bonding (Metal, Glass, Ceramics, Wood, Plastics)	
Features	<ul style="list-style-type: none"> ● General purpose ● Room temperature curing ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	Transparent	Yellow Brown, Transparent
Color After Curing	Yellow, Transparent	
Main Component	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	20000	40000
Specific Gravity (d ₄ ²⁰)	1.17	0.98
Mixing Ratio	100 : 100	
Pot Life at 25°C	1h	
Curing Time	24h	
Tensile Shear Strength (N/mm ²)	13	
Hardness (Shore D)	80	
Shelf Life	1year	
Volume / Packaging	2kgset Round metal can	

Flexibility Two-Component

Two-component epoxy adhesive cures to flexible material.

Maintains Flexibility After Curing

Even after curing, it retains its flexibility after being left for two years under conditions involving temperature fluctuations and UV exposure.



Easy Mixing

Simply transfer the entire contents of the hardener into the min part bottle and mix — no measuring required. The mixture can be used directly from the bottle, minimizing mess and ensuring clean handling.



Product Number	4100MIGHTY ■	
	Base Resin	Hardener
Applications	<ul style="list-style-type: none"> ● Support legs ● For areas requiring flexibility 	
Features	<ul style="list-style-type: none"> ● Applicable on wet surfaces ● Room temperature curing ● No measuring required ● Low-VOC / Low formaldehyde - JAIA F★★★★ / 4-VOC standard 	
Appearance	Transparent	Yellow Brown, Transparent
Color After Curing	Yellow, Transparent	
Main Component	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	1900	700
Specific Gravity (d ₄ ²⁰)	1.14	1.02
Mixing Ratio	100 : 100	
Pot Life at 25°C	40min	
Curing Time	24h	
Tensile Shear Strength (N/mm ²)	5	
Hardness (Shore A)	55	
Shelf Life	1year	
Volume / Packaging	Base resin : 100g Plastic jar Hardener : 100g Plastic jar	

■ Made to order

Epoxy Adhesives

Heat Resistance Two-Component

Room temperature curing epoxy adhesives with high heat resistance.

For Heat-Sensitive Areas Requiring Thermal Resistance

■ Heat and Chemical Resistance

Heat resistance at 150°C.

■ Room Temperature Curing

No thermal curing or heating equipment required thanks to room-temperature curing.

■ Low Curing Shrinkage

Solvent free, virtually no shrinkage upon curing.

■ For Large or On-Site Bonding Without Heat

Examples include:

- Vehicles, ships, and aircraft
- Tanks, ducts, and other piping systems
- Ceramics
- Electrical and electronic components



Heat Resistant Two-Component Epoxy Adhesive Clear Version

■ Heat and Chemical Resistance

Heat resistance at 150°C.

■ Room Temperature Curing

No thermal curing or heating equipment required thanks to room-temperature curing.

■ Low Curing Shrinkage

Solvent free, virtually no shrinkage upon curing.

■ Low Viscosity

Its low viscosity makes it easy to apply and suitable for bonding large surface areas.

■ For Large or On-Site Bonding Without Heat

Examples include:

- Vehicles, ships, and aircraft
- Tanks, ducts, and other piping systems
- Electrical and electronic components



No Continuous Adhesion Loss at 200°C

■ Heat and Chemical Resistance

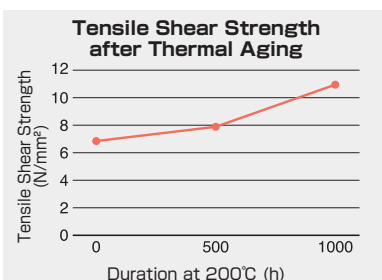
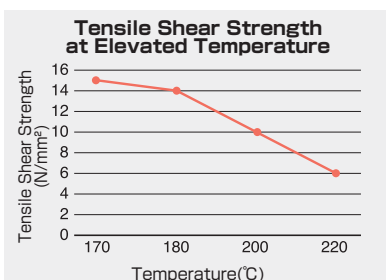
Heat resistance at 200°C.

■ Room Temperature Curing

No thermal curing or heating equipment required thanks to room-temperature curing.

■ Low Curing Shrinkage

Solvent free, virtually no shrinkage upon curing.



Product Number	3500	
	Base Resin	Hardener
Appearance	Dark Green	Beige
Color After Curing	Dark Green	
Main Component	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	Paste	Paste
Specific Gravity (d ₄ ²⁰)	1.31	1.50
Mixing Ratio	100 : 50	
Pot Life at 25°C	1h	
Curing Time	24h (RT) / 30min (80°C)	
Tensile Shear Strength (N/mm²)	20 (RT) / 11 (150°C)	
Hardness (Shore D)	83	
Shelf Life	3months	
Volume / Packaging	990g set Plastic jar Base resin 660g Hardener 330g	

Abbreviations : RT = Room Temperature

Product Number	3600	
	Base Resin	Hardener
Appearance	Reddish Brown, Transparent	Yellow, Transparent
Color After Curing	Dark Brown, Transparent	
Main Component	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	24000	1300
Specific Gravity (d ₄ ²⁰)	1.16	1.01
Mixing Ratio	100 : 32	
Pot Life at 25°C	5h	
Curing Time	24h (RT) / 30min (80°C)	
Tensile Shear Strength (N/mm²)	17 (RT) / 11 (150°C)	
Hardness (Shore D)	80	
Shelf Life	6months	
Volume / Packaging	1kg set Round can Base resin 758g Hardener 243g	

Product Number	3900	
	Base Resin	Hardener
Appearance	Yellow, Transparent	Brown, Transparent
Color After Curing	Dark Brown, Transparent	
Main Component	Modified epoxy resin	Modified polyamine
Viscosity (mPa·s / 25°C)	31000	3100
Specific Gravity (d ₄ ²⁰)	1.21	1.03
Mixing Ratio	100 : 25	
Pot Life at 25°C	100min	
Curing Time	24h (RT) / 60min (80°C)	
Tensile Shear Strength (N/mm²)	14 (RT) / 10 (200°C)	
Hardness (Shore D)	80	
Shelf Life	6months	
Volume / Packaging	1kg set Round can Base resin 750g Hardener 250g	

Test method: In accordance with JIS K 6833 (1994), ■ Made to order general test methods for adhesives.
In accordance with JIS K 6850 (1999), tensile shear adhesive strength testing method for adhesives and rigid substrates.



Standard Product **One-Component**

One-component epoxy adhesive for bonding various substrates.

■ For Bonding Various Substrates

Ideal for metal, glass, plastics.

■ Superior Properties with Mild Curing

With a recommended curing condition of 30 minutes at 100°C, this one-component epoxy adhesive cures under relatively mild conditions while offering excellent adhesion and thermal properties.

■ Low Halogen

The total chlorine and bromine content is less than 1500 ppm.



Product Number	AY-5302 ■
Applications	General purpose bonding
Features	Standard product line
Specific Gravity (d_{4}^{20})	1.2
Curing Time	30min (100°C)
Appearance	Gray
Viscosity (mPa·s)	5000
Hardness (Shore D)	83
Elastic Modulus (GPa)	3.1
Tg (°C)	108
Coefficient of Thermal Expansion (before Tg) (ppm)	60
Tensile Shear Strength (N/mm ²)	23
Temperature Range (°C)	~150
Volume	250g
Pot Life at 25°C	1 month
Storage Conditions	Frozen

Test method: In accordance with JIS K 6833 (1994), ■ Made to order general test methods for adhesives.

Low Temperature and Fast Curing **One-Component**

One-component thermal curing epoxy adhesive that cures at low temperatures and within a short curing time.

■ Low Temperature and Fast Curing

Short curing time does not thermally damage bonding parts and surrounding components and materials.

■ Low Halogen

The total chlorine and bromine content is less than 1500 ppm.



Product Number	AY-5231 ■	AY-5274 ■	AY-5404 ■
Applications	Camera module Heat sensitive devices	Camera module Heat sensitive devices	Camera module Heat sensitive devices Potting
Features	Low temperature and fast curing Low viscosity	Low temperature and fast curing Medium viscosity	Low temperature and fast curing High viscosity
Specific Gravity (d_{4}^{20})	1.2	1.2	1.5
Curing Time	20min (80°C)	20min (80°C)	15min (80°C)
Appearance	Black	Black	Black
Viscosity (mPa·s)	1500	4000	10000
Hardness (Shore D)	75	78	71
Elastic Modulus (GPa)	3.7	3.4	7.8
Tg (°C)	45	56	43
Coefficient of Thermal Expansion (before Tg) (ppm)	55	70	40
Tensile Shear Strength (N/mm ²)	25	21	22
Temperature Range (°C)	~150	~150	~150
Volume	250g	250g	250g
Pot Life at 25°C	10 days	10 days	10 days
Storage Conditions	Frozen	Frozen	Frozen

■ Made to order

Epoxy Adhesives

Heat Resistance, High Strength **One-Component**

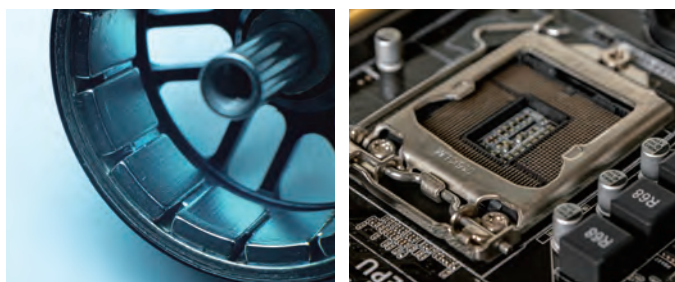
Thermal curing one-component epoxy resin adhesive for application requiring heat resistance and high strength, such as motor magnet bonding and electronic component potting.

■ Heat Resistance

High glass transition temperature (T_g) provides excellent heat resistance.

■ Superior Properties with Mild Curing

With high bonding strength and hardness, ideal for structural bonding and potting.



Product Number	AY-5011 ■	AY-5259 ■
Applications	Motor magnet Potting	Automotive motor Epoxy wafer lens Encapsulation Potting
Features	High strength Heat resistance Ultra high viscosity	High T _g Heat resistance High hardness Low halogen
Specific Gravity (d ₄ ²⁰)	1.2	1.5
Curing Time	60min (120°C)	60min (120°C)
Appearance	Gray	Black
Viscosity (mPa·s)	120000	6000
Hardness (Shore D)	87	91
Elastic Modulus (GPa)	2.4	8.4
T _g (°C)	155	191
Coefficient of Thermal Expansion (before T _g) (ppm)	65	35
Tensile Shear Strength (N/mm ²)	29	15
Temperature Range (°C)	~180	~190
Volume	250g	250g
Pot Life at 25°C	1month	1day
Storage Conditions	Frozen	Frozen

Test method: In accordance with JIS K 6833 (1994), ■ Made to order general test methods for adhesives.

For Electronic Components and Devices **One-Component**

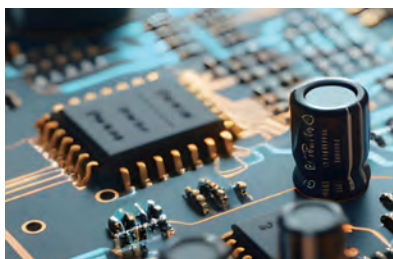
A one-component thermal curing epoxy adhesive suitable for applications requiring high environmental resistance and excellent mechanical properties, such as reinforcement of electronic components and circuits.

■ Properties Tailored to the Operating Conditions

Adhesive properties are tailored to the specific application, such as high reliability, high hardness, and flexibility.

■ Low halogen

The total chlorine and bromine content is less than 1500 ppm.



Product Number	AY-5158 ■	AY-5455 ■	AY-5013 ■
Applications	Reinforcement for IC chips	Adhesion Sealing of automotive electrical components	Piezoelectric (PZT) elements Flip chip bonding
Features	High reliability	High hardness	Flexible Stress release bonding
Specific Gravity (d ₄ ²⁰)	1.7	1.5	1.2
Curing Time	10min (100°C)	15min (110°C)	15min (80°C)
Appearance	Black	Black	Translucent
Viscosity (mPa·s)	20000	40000	1250
Hardness (Shore D)	79	95	50/80(Shore A)
Elastic Modulus (GPa)	4.3	10	12MPa
T _g (°C)	64	126	7
Coefficient of Thermal Expansion (before T _g) (ppm)	39	50	70
Tensile Shear Strength (N/mm ²)	24	17	9
Temperature Range (°C)	~150	~150	~120
Volume	250g	250g	250g
Pot Life at 25°C	1day	1month	10days
Storage Conditions	Frozen	Frozen	Frozen

■ Made to order



For Underfill **One-Component**

A one-component, thermal curing epoxy adhesive suitable for underfill and sidefill applications.

Low Temperature, Fast Curing

Short curing time does not thermally damage bonding parts and surrounding components and materials.

Low Viscosity

Low viscosity applicable for underfill.

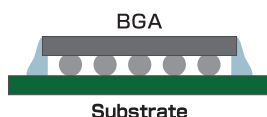
Low halogen

The total chlorine and bromine content is less than 1500 ppm.



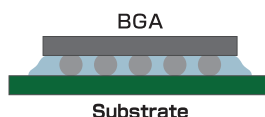
Sidefill

The adhesive capillary flows from the side of the electronic component. After flowing, thermally cure.



Underfill

Resin penetrates between the electronic component and the PCB by capillary action and is thermally cured.



Product Number	AY-5218C ■
Applications	Underfill, Sidefill
Features	Low viscosity
Specific Gravity (d_{4}^{20})	1.2
Curing Time	10min (100°C)
Appearance	Black
Viscosity (mPa·s)	1250
Hardness (Shore D)	70
Elastic Modulus (GPa)	1.3
Tg (°C)	36
Coefficient of Thermal Expansion (before Tg) (ppm)	80
Tensile Shear Strength (N/mm ²)	20
Temperature Range (°C)	~150
Volume	250g
Pot Life at 25°C	10days
Storage Conditions	Frozen

■ Made to order

Hybrid Curing **One-Component**

Combines the fast curing properties of light-curing adhesives with the high strength of epoxy resins.

Temporary Bonding by UV Curing

UV-induced temporary curing helps prevent adhesive flow during thermal curing and improves work efficiency.

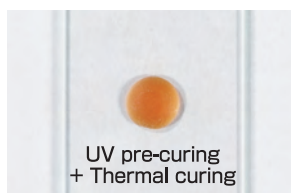
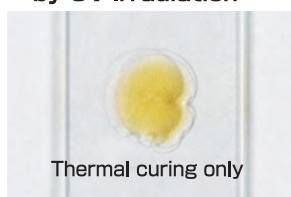
Final Strength is Achieved Through Thermal Curing

Thermal curing enables the adhesive to reach its final strength, delivering the high bonding performance typical of epoxy resin adhesives.

Low halogen

The total chlorine and bromine content is less than 1500 ppm.

Shape Retention by UV Irradiation



Product Number	AY-4112 ■
Applications	Potting, Molding
Features	B-staged by UV energy and fully cured by heat.
Specific Gravity (d_{4}^{20})	1.2
Curing Time	100mW/cm ² × 10sec + 1h (80°C)
Appearance	Pale Brown
Viscosity (mPa·s)	3000
Hardness (Shore D)	80
Elastic Modulus (GPa)	2.8
Tg (°C)	79/149
Coefficient of Thermal Expansion (before Tg) (ppm)	80
Tensile Shear Strength (N/mm ²)	17
Temperature Range (°C)	~150
Volume	250g
Storage Conditions	Frozen

■ Made to order

Hybrid

Light Curing
Acrylic Adhesive
(Fast Curing)

Thermal Curing
Epoxy Adhesive
(Bond Strength,
Low Out Gassing,
High Reliability)

Handling Precautions for Various Adhesives

Cyanoacrylate Adhesives

Precautions for Use



In Case of Contact with Skin

Do not forcefully peel it off. Soak the area in warm water (around 40°C) and gently rub until it loosens, or use a dedicated debonding agent or a solvent such as acetone.



In Case of Contact with Eyes

Rinse thoroughly with clean water repeatedly and seek medical attention. Do not rub your eyes or use any debonding agent or solvent such as acetone.



In Case of Inhalation

Move to a place with fresh air and rinse your mouth. If symptoms persist, consult a physician.



In Case of Ingestion

Small amounts solidify quickly. Rinse your mouth with plenty of water and gently remove any hardened adhesive by hand. In the case of large amounts, burns may occur - cool the area with water and seek immediate medical attention.



In Case of Spillage

Large amounts spilled on cloth may generate heat and cause burns - handle with care. It may not be removable once absorbed. If spilled on surfaces such as desks, wear polyethylene gloves and wipe off gradually before it cures. Once cured, test a small, inconspicuous area for surface damage before using acetone or similar solvent to remove it gradually.



Work Environment

Ensure adequate ventilation, as the product emits a strong odor. Prolonged or repeated exposure may irritate the eyes, throat, and nose. Take regular breaks in fresh air to protect your health. Also, use the product in a fire-free environment.

Precautions After Use



Wipe off the nozzle tip after use and securely cap the container. Store in a cool, dry, and dark place away from fire sources.



Avoid exposure to direct sunlight, as the adhesive may also cure under ultraviolet light.



Keep out of reach of infants and young children, and take precautions to avoid misuse.



Do not store the product in alkaline environments or near curing accelerators or amine-based substances.

Disposal Instructions

- Expose small amounts of the adhesive to direct sunlight to cure, then dispose of it as plastic waste.
- Dispose of the product in accordance with local disposal regulations.

Epoxy Adhesives

Anaerobic Adhesives / Light-Cure Adhesives

Precautions for Use



In Case of Contact with Skin

Wipe off immediately and wash thoroughly with soap and water or warm water. If itching or inflammation occurs, seek medical attention promptly.



In Case of Contact with Eyes

Rinse thoroughly with plenty of water immediately and consult a physician as soon as possible.



In Case of Inhalation

If abnormal symptoms such as itching occur due to inhalation of fumes or vapor, seek medical attention immediately.



In Case of Ingestion

Do not induce vomiting. Seek medical attention promptly.



In Case of Spillage

Wipe up with paper or cloth. If a large amount is spilled, collect it in a sealed container.



Work Environment

Install local exhaust ventilation in work areas where mixing, dispensing, application, or bonding is carried out.



In Case of Fire

Cut off any sources of combustion and extinguish the fire from upwind using an appropriate fire extinguisher, such as a dry chemical (ABC type) or carbon dioxide (CO₂) extinguisher.



Proper Workwear

Wear impermeable gloves and long-sleeved work clothing to prevent direct contact with the body. Avoid handling the product directly with bare hands.

Precautions After Use



Wipe the container and nozzle tips clean, replace the cap, and store under the specified conditions.



Wash hands and gargle thoroughly after use.



Keep out of reach of infants and young children, and take precautions to avoid misuse.

Disposal Instructions

- Dispose of the product in accordance with applicable local laws and regulations, or entrust disposal to a licensed waste disposal contractor. Dispose of used containers and cloths in the same manner.

Glossary of Adhesives Terms

Set Time

Time required for the bonded parts to cure sufficiently to be handled or moved to the next process without damage. JIS defines it as the time it takes to withstand a 50N force.

Tensile Shear Strength

Maximum load at which the bonded test specimen fails when a tensile shear force is applied, divided by the bonded area.

Compressive Shear Strength

Maximum load at failure under compressive shear force, divided by the bonded area.

Pot Time

Time during which the mixed adhesive remains usable for application. Typically defined as the time to double the initial viscosity or reach 60% of the exothermic peak.

Curing Time

Time at which the adhesive begins to exhibit stable mechanical properties such as tensile, compressive strength, or hardness.

Thixotropic

Property of a material that is gel-like at rest but becomes fluid when agitated or stirred, and returns to gel-like state upon resting.

Break Torque

The torque required to start turning a fastener after the adhesive has fully cured.

Prevail Torque

The torque needed to continue turning a fastener after the initial breakaway, due to residual cured adhesive in the thread gaps.

Maximum Applicable Gap

The maximum bond gap between substrates that still allows for sufficient bonding strength.

Pot Life

Time after mixing during which the adhesive remains in a usable, applicable state.

UV Intensity

Measured radiant energy of ultraviolet light used for curing.

Tg (Glass Transition Temperature)

The temperature at which a cured material transitions from a hard, glassy state to a soft, rubbery state.

Coefficient of Thermal Expansion

The rate at which a material's length changes with temperature.

The data provided in this catalog are for reference only and may differ under actual conditions.
They do not guarantee product performance.
Before use, please conduct sufficient testing to ensure suitability for your specific application.
Please note that product design and appearance are subject to change without prior notice.
Refer to the Safety Data Sheet (SDS) issued by our company and ensure safe usage under your own responsibility.
All chemical products may have unknown hazards; therefore, handle them with due care.

ALTECO INC.

Head Office: 5-8, Nishiekimaecho, Ibaraki-City, Osaka 567-0032
TEL: +81-726-27-1617 FAX: +81-726-27-1633
Tokyo Office: 2-7, Kandatacho, Chiyoda-ku, Tokyo 101-0046
TEL: +81-3-3518-5305 FAX: +81-3-3256-1533
Nagoya Office: 1-18-11, Nishiki, Naka-ku, Nagoya-City, Aichi 460-0003
TEL: +81-52-211-1340 FAX: +81-52-232-1518

■ URL <https://www.alteco.co.jp/en>
■ E-mail info@alteco.co.jp



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